

REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD
1	△	Size change	17/JUL/19	KATE	CHERRY
2	△	Flammability Change	02/AUG/23	MATT	LEO

Electrical

Current Rating: 13A AC(rms)/DC
Voltage Rating: 300V AC(rms)/DC
Contact Resistance: 20 mΩ Max
Insulation Resistance: 1000 MΩ MIN
Withstanding Voltage: 1500V AC r.m.s
Temperature Range—Operating: -25°C~+85°C

Material and Plating


Housing: PA66(UL 94V-2) △
Contact Pin: Brass
Plating: Tin Plated

Circuits (n)	Part No.	Dimensions(in/mm)
		A
2	FWF63501-S02S22TB	.250(6.35)
3	FWF63501-S03S22TB	.500(12.70)
4	FWF63501-S04S22TB	.750(19.05)
5	FWF63501-S05S22TB	1.00(25.40)

Ordering Information

FWF 635 01 - S XX S 2 2 T B
1 2 3 4 5 6 7 8 9 10

1 Category FWF—Wafer	2 Series Number 635—Pitch6.35mm	3 Distinction No. 01	4 Row Option S—Single Row	5 Circuits XX	6 Entry Angle S—180°Vertical
7 Plating 2—Tin Plated	8 Material—Resin 2—PA66	9 Color—Resin T—Transparent	10 Packaging B—PE Bag		

THIRD ANGLE PROJECTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY FRANK	DATE 28/JUN/13	PART NO. FWF63501-SXXS22TB	ITEM NO. FWF63501	 Leader Of Industry
	DESIGN UNITS Inch (metric)	X.±.012(0.30) X.X±.008(0.20) X.XX±.006(0.15) X.XXX±.004(0.10)	X'±5' .X'±2' .XX'±1' .XXX'±0.5'	CHECKED BY JACOB	DATE 28/JUN/13	TITLE Wire to Board (Wafer) Pitch 6.35mm 180° Vertical (DIP)	
SCALE 5:1	SIZE A4	DRAWN BY CHERRY		DATE 28/JUN/13	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

Recommended P.C.Board Layout

